

ABSTRACT

A ceramic package and a chip resistor obtained by forming, on a plastic ceramic green sheet comprising 100 parts by weight of a ceramic powder mainly composed of borosilicate glass, into which 10 to 30 parts by weight of an acrylic copolymer obtained by polymerizing 100 parts by weight of a (meth)acrylic acid ester and 1 to 10 parts by weight of a monomer having a functional group of a hydroxyl group, acid amide group, or amino group and having a Tg in the range of -30°C to +10°C is compounded, a conductor layer using a plastic conductive paste obtained by compounding, into 100 parts by weight of a conductive powder, 5 to 20 parts a mixture of an acrylic copolymer having a Tg of not more than -30°C and an ethylcellulose-based binder, press forming the resultant single layer of ceramic green sheet, and calcining the resultant ceramic green sheet having the integrally formed bottom, opening and opening circumferential edge and a method for producing the same.